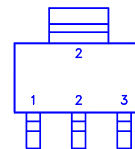
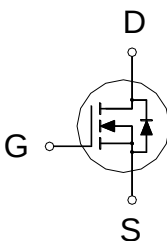


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
150V	48m Ω	5.5A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	5.5	A
	$T_A = 70\text{ }^{\circ}\text{C}$		4.4	
Pulsed Drain Current ¹		I_{DM}	23	
Avalanche Current		I_{AS}	14	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	74	mJ
Power Dissipation ³	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	3.5	W
	$T_A = 70\text{ }^{\circ}\text{C}$		2.2	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$t \leq 10\text{s}$	$R_{\theta JA}$		35	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient ²	Steady-State	$R_{\theta JA}$		52	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$.

³The Power dissipation is based on $R_{\theta JA}$ $t \leq 10\text{s}$ value.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

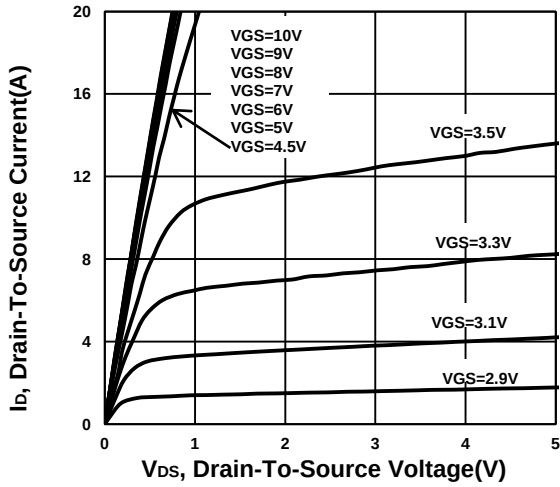
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	150			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	2.1	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 150V, V_{GS} = 0V$			1	μA
		$V_{DS} = 150V, V_{GS} = 0V, T_J = 55\text{ }^{\circ}C$			10	

Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 4.5V, I _D = 4A		44	60	mΩ
		V _{GS} = 10V, I _D = 4A		37	48	
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 4A		17		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 75V, f = 1MHz		1169		pF
Output Capacitance	C _{oss}			97		
Reverse Transfer Capacitance	C _{rss}			15		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		0.5		Ω
Total Gate Charge ²	Q _{g(VGS=10V)}	V _{DS} = 75V, I _D = 4A		21		nC
	Q _{g(VGS=4.5V)}			12		
Gate-Source Charge ²	Q _{gs}			3.4		
Gate-Drain Charge ²	Q _{gd}			6.3		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} = 75V I _D ≅ 4A, V _{GS} = 10V, R _{GS} = 6Ω		8		nS
Rise Time ²	t _r			21		
Turn-Off Delay Time ²	t _{d(off)}			23		
Fall Time ²	t _f			28		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _J = 25 °C)						
Continuous Current	I _S				2.9	A
Forward Voltage ¹	V _{SD}	I _F = 4A, V _{GS} = 0V			1.2	V
Reverse Recovery Time	t _{rr}	I _F = 4A, dI/dt = 100 A/μs		67		nS
Reverse Recovery Charge	Q _{rr}			97		nC

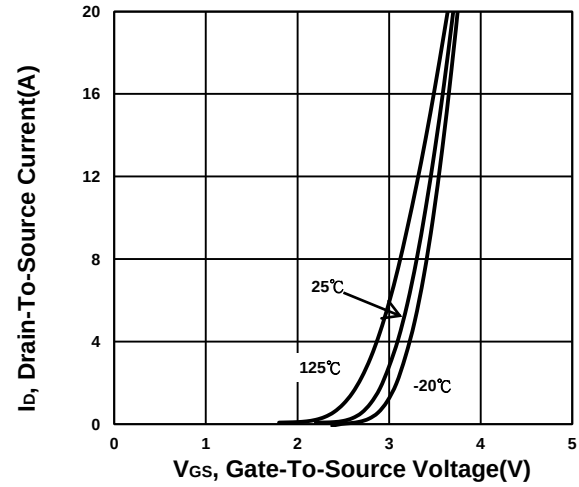
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

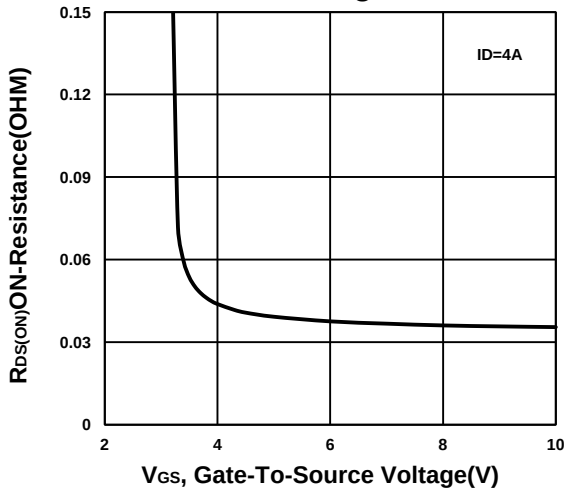
Output Characteristics



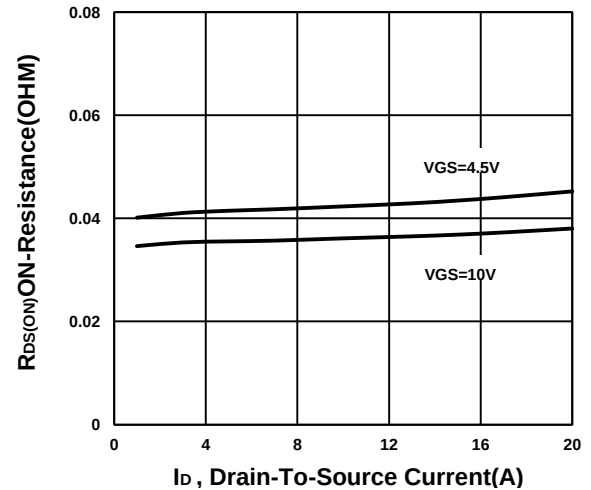
Transfer Characteristics



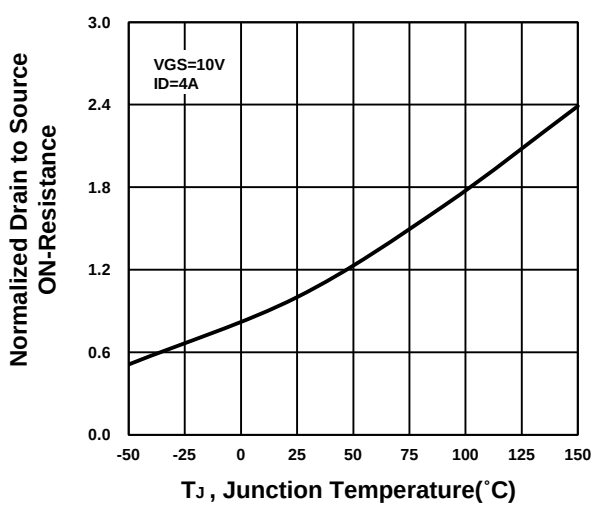
On-Resistance VS Gate-To-Source Voltage



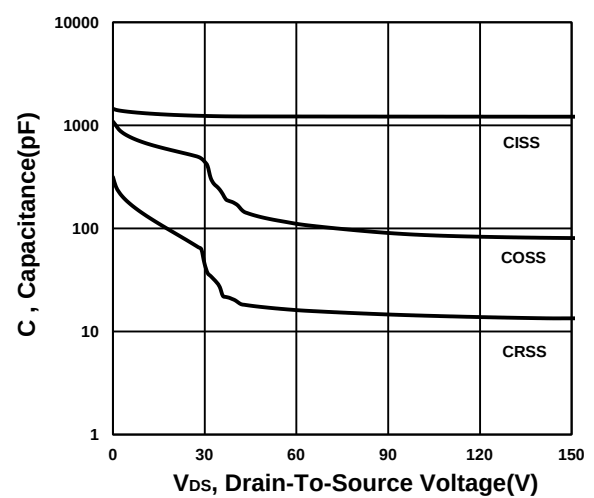
On-Resistance VS Drain Current



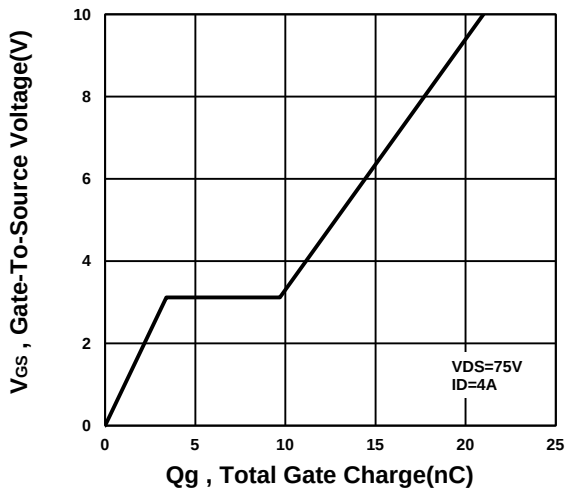
On-Resistance VS Temperature



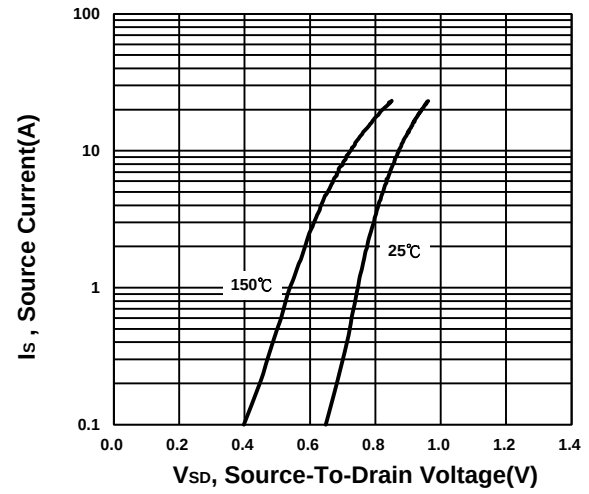
Capacitance Characteristic



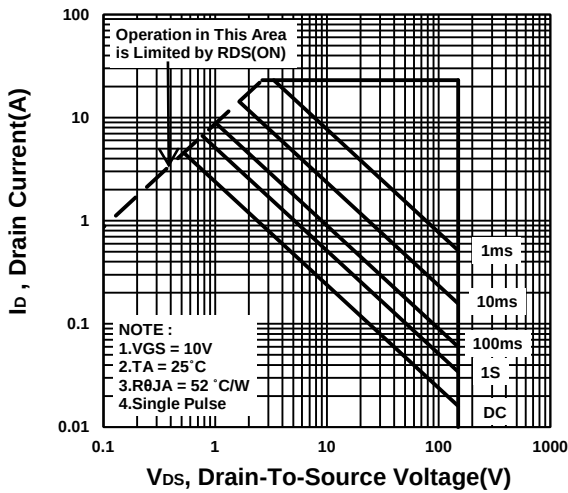
Gate charge Characteristics



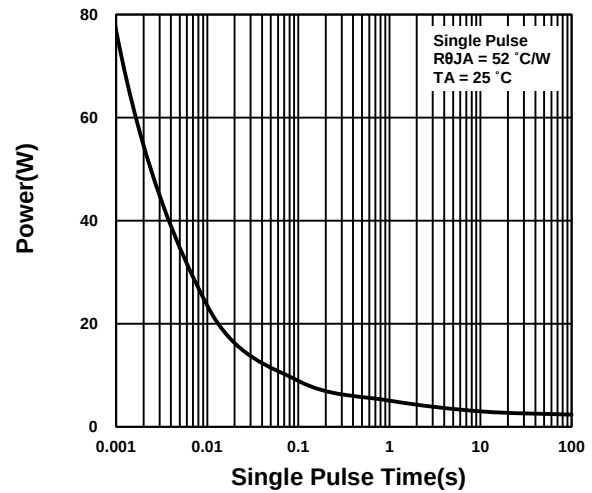
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

